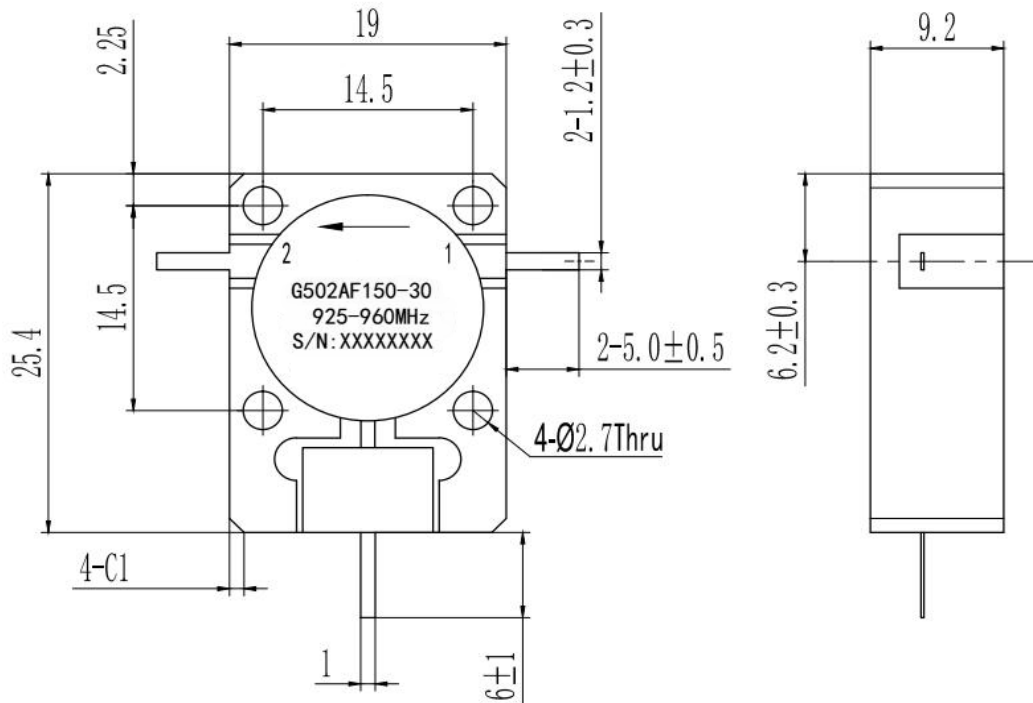


1.Features

- UMTS, LTE Band
- PCB Soldering Re-flow
- Wide Operation Temperature Range -40 ~ 85°C
- Compact Package Design for PCB Applications

2.Dimension



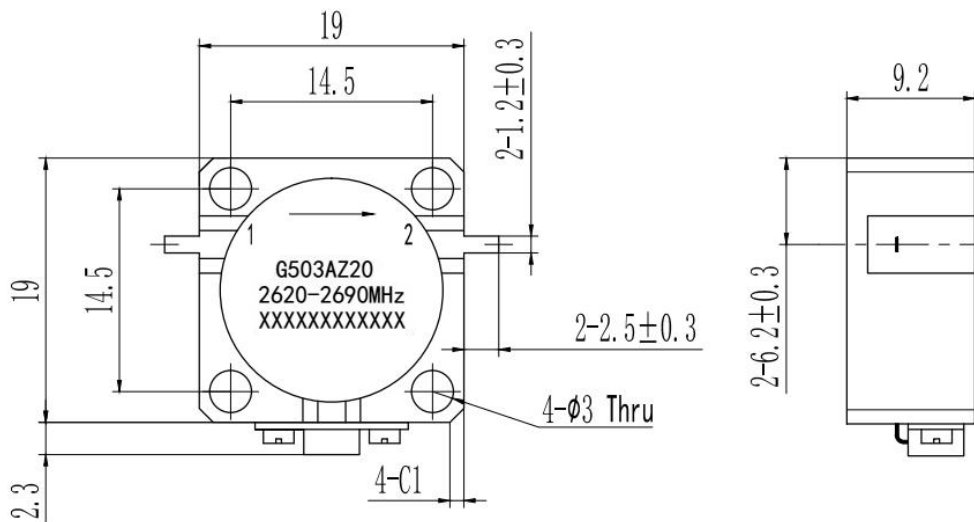
3.Specifications

Part No.	Frequency (GHz)		Center Frequency (GHz)	Bandwidth (GHz)	Isolation (dB) MIN	INS LOSS (dB) MAX	VSWR (dB) MAX	Power (W)	IMD (@2X43dBm) (-dBc) MAX
	F1	F2							
G502A[925-960]MHz	0.925	0.960	0.943	0.035	22	0.3	1.17	150	
G502A[1600-1630]MHz	1.600	1.630	1.6150	0.030	23	0.25	1.15	150	
G502A[1689-1710]MHz	1.689	1.710	1.6995	0.021	23	0.2	1.15	150	
G502A[1800-2200]MHz	1.800	2.200	2.0000	0.400	22	0.3	1.2	100	
G502A[1805-1880]MHz	1.805	1.880	1.8375	0.075	23	0.25	1.17	150	
G502A[2000-2500]MHz	2.000	2.500	2.2500	0.500	18	0.4	1.3	150	
G502A[2100-2200]MHz	2.100	2.200	2.1500	0.100	22	0.3	1.2	150	
G502A[2300-2400]MHz	2.300	2.400	2.3500	0.100	22	0.25	1.17	150	-65
G502A[2555-2660]MHz	2.555	2.660	2.6075	0.105	22	0.25	1.17	150	-65
G502A[3100-3500]MHz	3.100	3.500	3.3000	0.400	20	0.35	1.2	100	
G502A[3400-4200]MHz	3.400	4.200	3.800	0.800	15	0.45	1.4	150	

1.Features

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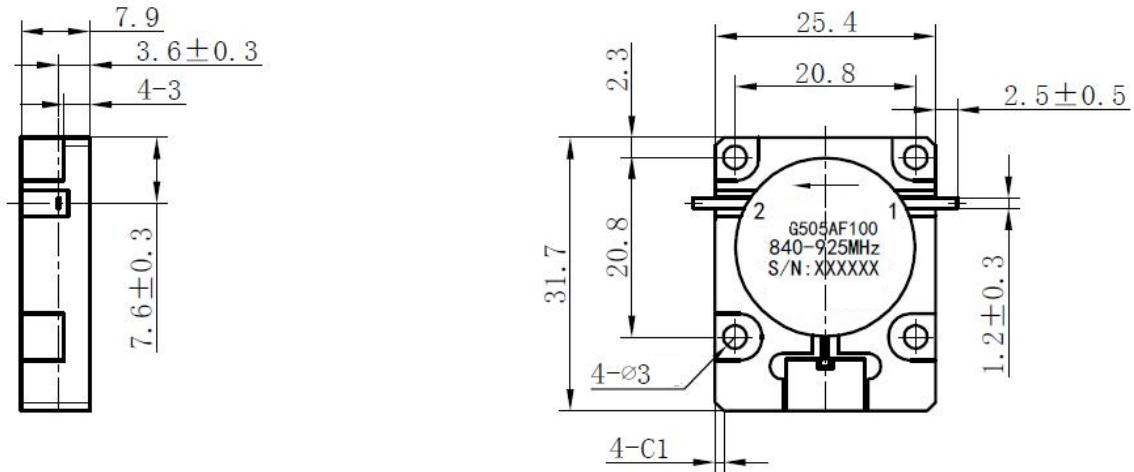
3.Specifications

Part No.	Frequency (GHz)		Center Frequency	Bandwidth	Isolation	INS LOSS	VSWR	Power	IMD (@2X43dBm)
	F1	F2	(GHz)	(GHz)	(dB) MIN	(dB) MAX	(dB) MAX	(W)	(-dBc) MAX
G503A[925-960]MHz	0.925	0.960	0.943	0.035	22	0.3	1.17	60	
G503A[1710-1785]MHz	1.710	1.785	1.7475	0.075	23	0.25	1.17	60	
G503A[1805-1880]MHz	1.805	1.880	1.8375	0.075	25	0.25	1.15	60	
G503A[1880-1920]MHz	1.880	1.920	1.9000	0.040	25	0.25	1.15	100	
G503A[1920-1980]MHz	1.920	1.980	1.9500	0.060	23	0.25	1.17	60	
G503A[1930-1990]MHz	1.930	1.990	1.9600	0.060	23	0.25	1.17	60	
G503A[2010-2025]MHz	2.010	2.025	2.0170	0.015	25	0.25	1.17	60	
G503A[2110-2170]MHz	2.110	2.170	2.1400	0.060	23	0.25	1.17	60	
G503A[2620-2690]MHz	2.620	2.690	2.6550	0.070	23	0.25	1.17	60	

1.Features

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2.Dimensions



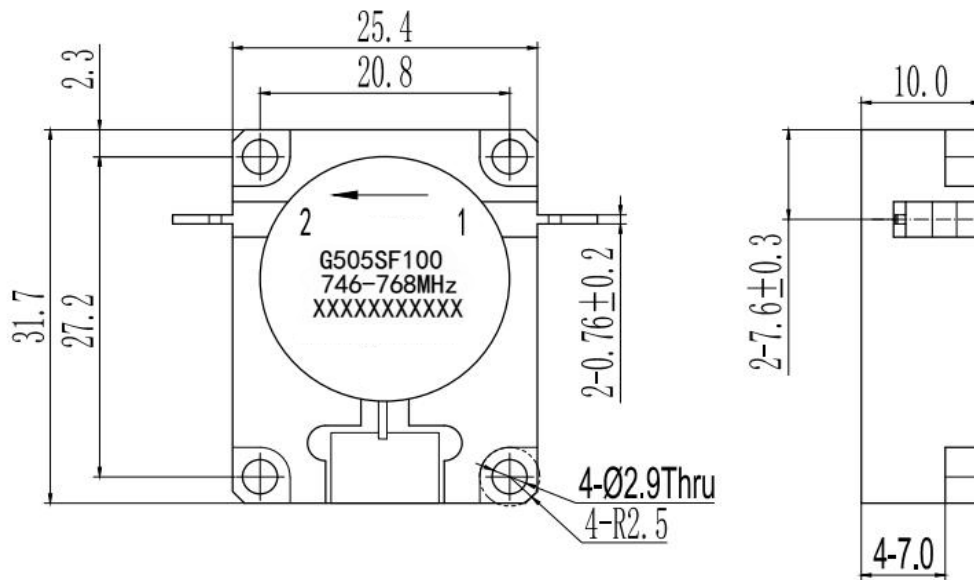
3.Specifications

Part No.	Frequency (GHz)		Center Frequency	Bandwidth	Isolation	INS LOSS	VSWR	Power	IMD (@2X43dBm)
	F1	F2	(GHz)	(GHz)	(dB) MIN	(dB) MAX	(dB) MAX	(W)	(-dBc) MAX
G505A[840-925]MHz	0.840	0.925	0.883	0.085	23	0.3	1.15	150	
G505A[869-894]MHz	0.869	0.894	0.882	0.025	23	0.325	1.15	150	-65
G505A[925-960]MHz	0.925	0.960	0.943	0.035	25	0.25	1.15	100	
G505A[1800-1950]MHz	1.800	1.950	1.8750	0.150	22	0.3	1.17	150	
G505A[1805-1880]MHz	1.805	1.880	1.8375	0.075	25	0.25	1.15	150	
G505A[1920-1980]MHz	1.920	1.980	1.9500	0.060	25	0.2	1.15	100	
G505A[1930-1990]MHz	1.930	1.990	1.9600	0.060	25	0.2	1.15	100	
G505A[2110-2170]MHz	2.110	2.170	2.1400	0.060	23	0.25	1.15	100	

1.Features

- UMTS, LTE Band
- PCB Soldering Re-flow
- Wide Operation Temperature Range -40 ~ 85°C
- Compact Package Design for PCB Applications

2.Dimensions Unit:mm



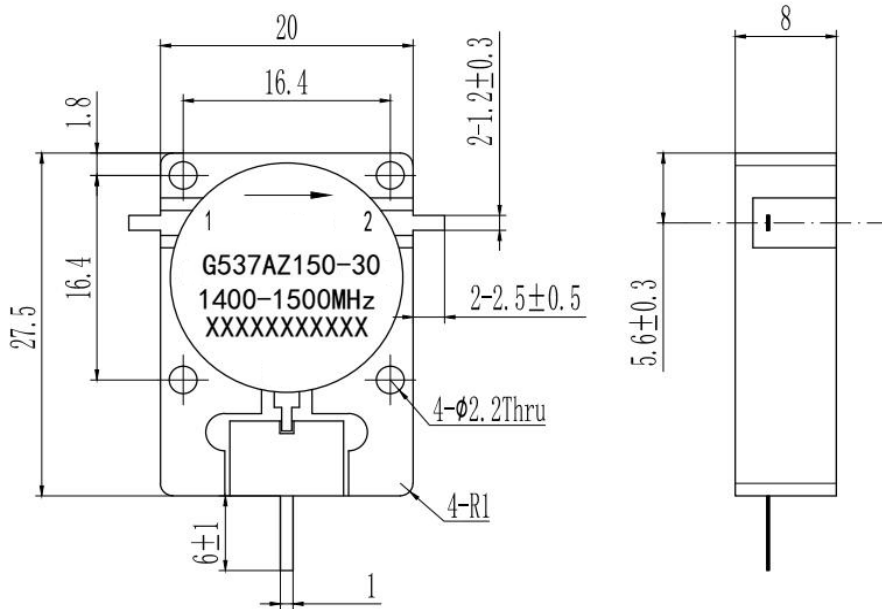
3.Specifications

Part No.	Frequency (GHz)		Center Frequency	Bandwidth	Isolation	INS LOSS	VSWR	Power	IMD (@2X43dBm)
	F1	F2	(GHz)	(GHz)	(dB) MIN	(dB) MAX	(dB) MAX	(W)	(-dBc) MAX
G505S [729-746]MHz	0.729	0.746	0.738	0.017	25	0.25	1.12	100	-70
G505S [746-768]MHz	0.746	0.768	0.757	0.022	25	0.25	1.12	100	-70
G505S [758-803]MHz	0.758	0.803	0.781	0.045	25	0.25	1.12	100	-70
G505S [791-821]MHz	0.791	0.821	0.805	0.030	25	0.25	1.12	100	-70
G505S [925-960]MHz	0.925	0.960	0.9425	0.035	25	0.25	1.12	100	-70
G505S [1805-1880]MHz	1.805	1.880	1.8375	0.075	25	0.25	1.12	100	-70
G505S [2110-2170]MHz	2.110	2.170	2.1400	0.060	25	0.25	1.12	100	-70

1.Features

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- PCB Soldering Re-flow
- Wide Operation Temperature Range -40 ~ 85°C
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2.Dimensions



3.Specifications

Part No.	Frequency (GHz)		Center Frequency	Bandwidth	Isolation	INS LOSS	VSWR	Power	IMD (@2X43dBm)
	F1	F2	(GHz)	(GHz)	(dB) MIN	(dB) MAX	(dB) MAX	(W)	(-dBc) MAX
G537A[851-866]MHz	0.851	0.866	0.859	0.015	25	0.25	1.15	150	
G537A[865-880]MHz	0.865	0.880	0.873	0.015	23	0.3	1.15	150	
G537A[869-894]MHz	0.869	0.894	0.8815	0.025	23	0.3	1.15	150	
G537A[880-920]MHz	0.880	0.920	0.9000	0.040	23	0.3	1.15	150	
G537A[920-960]MHz	0.920	0.960	0.9400	0.040	23	0.3	1.15	100	
G537A[1452-1492]MHz	1.452	1.492	1.4720	0.040	25	0.25	1.15	100	
G537A[1710-1755]MHz	1.710	1.755	1.7325	0.045	25	0.25	1.15	150	
G537A[1805-1880]MHz	1.805	1.880	1.8375	0.075	23	0.25	1.15	100	
G537A[1805-1920]MHz	1.805	1.920	1.8625	0.115	22	0.25	1.17	100	
G537A[1920-1980]MHz	1.920	1.980	1.9500	0.060	23	0.25	1.15	150	
G537A[2010-2025]MHz	2.010	2.025	2.0175	0.015	23	0.25	1.15	100	
G537A[2110-2170]MHz	2.110	2.170	2.1400	0.060	23	0.25	1.15	150	
G537A[2400-2500]MHz	2.400	2.500	2.4500	0.100	23	0.25	1.15	100	
G537A[2620-2690]MHz	2.620	2.690	2.6550	0.070	23	0.25	1.15	150	

Drop-in Isolator

Features:

- UMTS, LTE Band
- PCB Soldering Re-flow
- Compact Package Design for PCB Applications



ELECTRICAL CHARACTERISTICS:

Model	Freq (GHz)	Bandwidth (MHz,max.)	Insertion Loss (dB,max.)	Isolation (dB,min.)	VSWR (dB,min.)	Forward Power (W,max)	Backward Power (W)	Temperature (°C)	Dimensions (mm)
G6060H	0.02-0.4	175	2	18	1.3	100	10-100	-20 - +70	60*60*25.5
G6466H	0.02-0.4	175	2	18	1.3	100	10-100	-10 - +60	64*66*22
G7070X	0.13-2	30	0.6	10	1.3	500	10-100	-20 - +70	70*70*15
G5050X	0.16-0.33	70	0.7	18	1.3	500	10-100	-30 - +70	50.8*50.8*14.8
G4545X	0.3-1.1	300	0.6	19	1.3	500	10-100	-30 - +70	45*45*13
G3538X	0.3-1.85	500	0.7	18	1.35	300	10-100	-30 - +70	35*38*11
G3546X	0.3-1.85	500	0.7	18	1.35	300	100	-30 - +70	35*46*11
G2525X	0.35-4	770	0.65	15	1.45	250	10-100	-30 - +70	25.4*25.4*10
G2532X	0.35-4	770	0.65	15	1.45	250	100	-30 - +70	25.4*31.7*10
G5032X	0.45-2.7	400	0.8	38	1.25	250	10-100	-30 - +70	50.8*31.7*10
G4020X	0.6-2.7	400	0.8	40	1.2	100	10-100	-30 - +70	40*20*8.6
G4027X	0.6-2.7	400	0.8	40	1.2	100	10-100	-30 - +70	40*27.5*8.6
G2027X	0.6-3.6	900	0.5	18	1.35	150	100	-30 - +70	20*27.5*8.6
G2020X	0.6-4	900	0.5	18	1.35	150	20	-30 - +70	20*20*8.6
G1919X	0.8-4.3	900	0.5	18	1.35	100	20	-30 - +70	19*19*8.6
G1925X	0.8-4.3	900	0.5	18	1.35	100	100	-30 - +70	19*19*8.6
G6466K	0.95-2	1050	0.65	16	1.4	100	10-100	0 - +60	64*66*26
G5050A	1.5-3	1500	0.7	17	1.4	100	10-100	-10 - +60	50.8*49.5*19
G1313M	1.7-6	800	0.45	18	1.3	60	20	-30 - +70	12.7*12.7*7.2
G1313T	1.7-6	800	0.45	18	1.3	60	20	-30 - +70	12.7*12.7*7.2
G3234A	2-4	2000	0.6	18	1.3	100	10-100	-10 - +60	32*34*21
G1626D	3.7-5	1000	0.5	18	1.3	100	10	-30 - +70	16*26*10.5
G2528C	3-6	3500	0.8	16	1.4	60	20	-10 - +60	25.4*28*14
G2123B	4-8	4000	0.6	18	1.35	60	20	0 - +60	21*22.5*15
G1220D	5-7	800	0.5	18	1.3	80	10	-30 - +70	12*20*9.5
G1623D	5-7	800	0.5	18	1.3	100	10	-30 - +70	16*23*9.7
G0915D	7-18	6000	0.6	17	1.35	30	10	-30 - +70	8.9*15*7.8
G1622B	6-18	12000	1.5	11	1.9	30	10	0 - +60	16*21.5*14